



Full Material Declaration for attached parts list

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Declarations authorised by
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Declaration effective from: 01 January 2014 [Approved: 13 August 2024 07:04 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.02%	ALUMINIUM	7429-90-5	1%
			Gold	7440-57-5	1%
			Silicon	7440-21-3	98%
			Carbon black	1333-86-4	1%
Encapsulation	EP (Epoxy resin)	28.95%	2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane	1675-54-3	10%
			Aluminum oxide trihydrate	21645-51-2	10%
			Epoxy resin 89	26335-32-0	19%
			Quartz sand	60676-86-0	60%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.02%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	8.15%	Tin	7440-31-5	100%
Leadframe	Steel and iron materials	62.86%	Elemental nickel	7440-02-0	42.5%
			REACH Article 67 Exemption		
			Iron	7439-89-6	57.5%

Attached parts list

Part number	Part name
SOD-123_PbF_HF	Diode SMD